

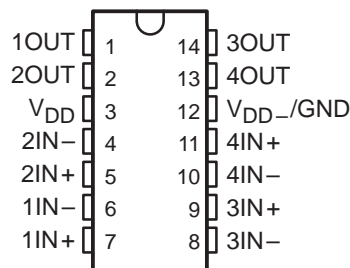
TLC354

LinCMOS™ QUADRUPLE DIFFERENTIAL COMPARATORS

SLCS116B – SEPTEMBER 1985 – REVISED FEBRUARY 1997

- **Single- or Dual-Supply Operation**
- **Wide Range of Supply Voltages**
1.4 V to 18 V
- **Very Low Supply Current Drain**
300 μ A Typ at 5 V
130 μ A Typ at 1.4 V
- **Built-In ESD Protection**
- **High Input Impedance . . . $10^{12} \Omega$ Typ**
- **Extremely Low Input Bias Current**
5 pA Typ
- **Ultrastable Low Input Offset Voltage**
- **Input Offset Voltage Change at Worst-Case Input Conditions Typically 0.23 μ V/Month, Including the First 30 Days**
- **Common-Mode Input Voltage Range Includes Ground**
- **Outputs Compatible With TTL, MOS, and CMOS**
- **Pin-Compatible With LM339**

D, N, OR PW PACKAGE
(TOP VIEW)



symbol (each comparator)



description

This device is fabricated using LinCMOS™ technology and consists of four independent differential voltage comparators; each is designed to operate from a single power supply. Operation from dual supplies is also possible if the difference between the two supplies is 1.4 V to 18 V. Each device features extremely high input impedance (typically greater than $10^{12} \Omega$), which allows direct interface to high-impedance sources. The outputs are n-channel open-drain configurations and can be connected to achieve positive-logic wired-AND relationships. The capability of the TLC354 to operate from a 1.4-V supply makes this device ideal for low-voltage battery applications.

The TLC354 has internal electrostatic discharge (ESD) protection circuits and has been classified with a 2000-V ESD rating tested under MIL-STD-883C, Method 3015. However, care should be exercised in handling this device as exposure to ESD may result in degradation of the device parametric performance.

The TLC354C is characterized for operation from 0°C to 70°C. The TLC354I is characterized for operation over the industrial temperature range of -40° to 85°C. The TLC354M is characterized for operation over the full military temperature range -55°C to 125°C.

AVAILABLE OPTIONS

T _A	V _{IO} max AT 25°C	PACKAGED DEVICES			CHIP FORM (Y)
		SMALL OUTLINE (D)	PLASTIC DIP (P)	TSSOP (PW)	
0°C to 70°C	5 mV	TLC354CD	TLC354CN	TLC354CPW	TLC354Y
-40°C to 85°C	5 mV	TLC354ID	TLC354IN	—	—
-55°C to 125°C	5 mV	TLC354MD	TLC354MN	—	—

The D packages are available taped and reeled. Add R suffix to device type (e.g., TLC354CDR).



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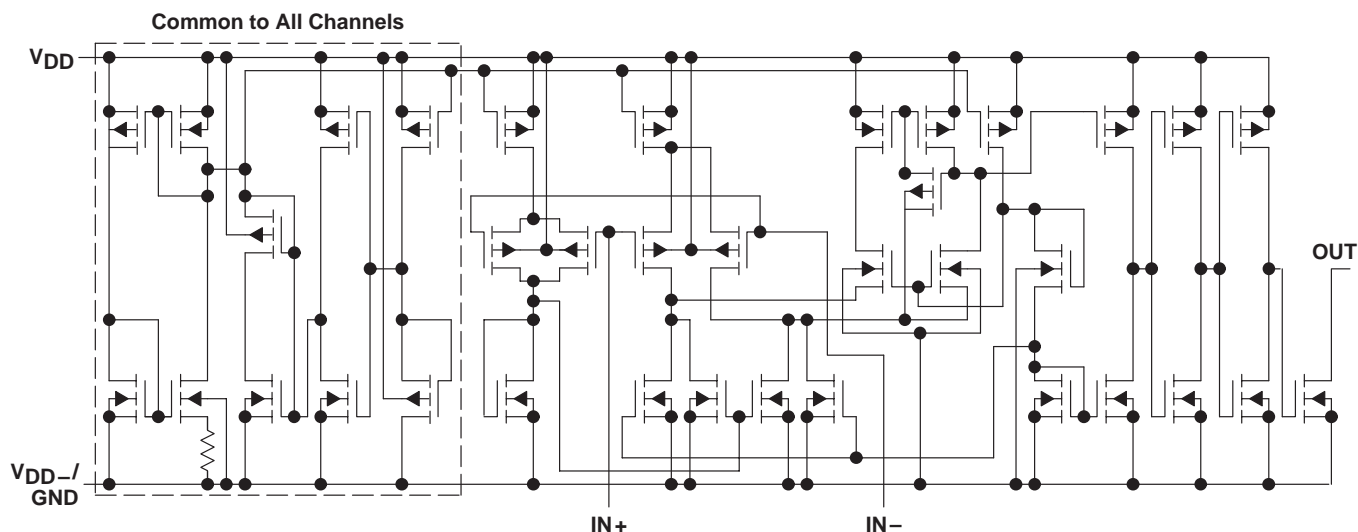
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TLC354 LinCMOS™ QUADRUPLE DIFFERENTIAL COMPARATORS

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equivalent schematic (each comparator)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1)	18 V
Differential input voltage, V_{ID} (see Note 2)	± 18 V
Input voltage, V_I	V_{DD}
Input voltage range, V_I	-0.3 V to 18 V
Output voltage, V_O	18 V
Input current, I_I	± 5 mA
Output current, I_O	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : TLC354C	0°C to 70°C
TLC354I	-40°C to 85°C
TLC354M	-55°C to 125°C
Storage temperature range	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values except differential voltages are with respect to network ground.
 2. Differential voltages are at IN+ with respect to IN-.
 3. Short circuits from outputs to V_{DD} can cause excessive heating and eventual device destruction.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	500 mW	7.6 mW/°C	84°C	500 mW	494 mW	190 mW
N	500 mW	9.2 mW/°C	96°C	500 mW	500 mW	230 mW
PW	700 mW	5.6 mW/°C	25°C	448 mW	N/A	N/A



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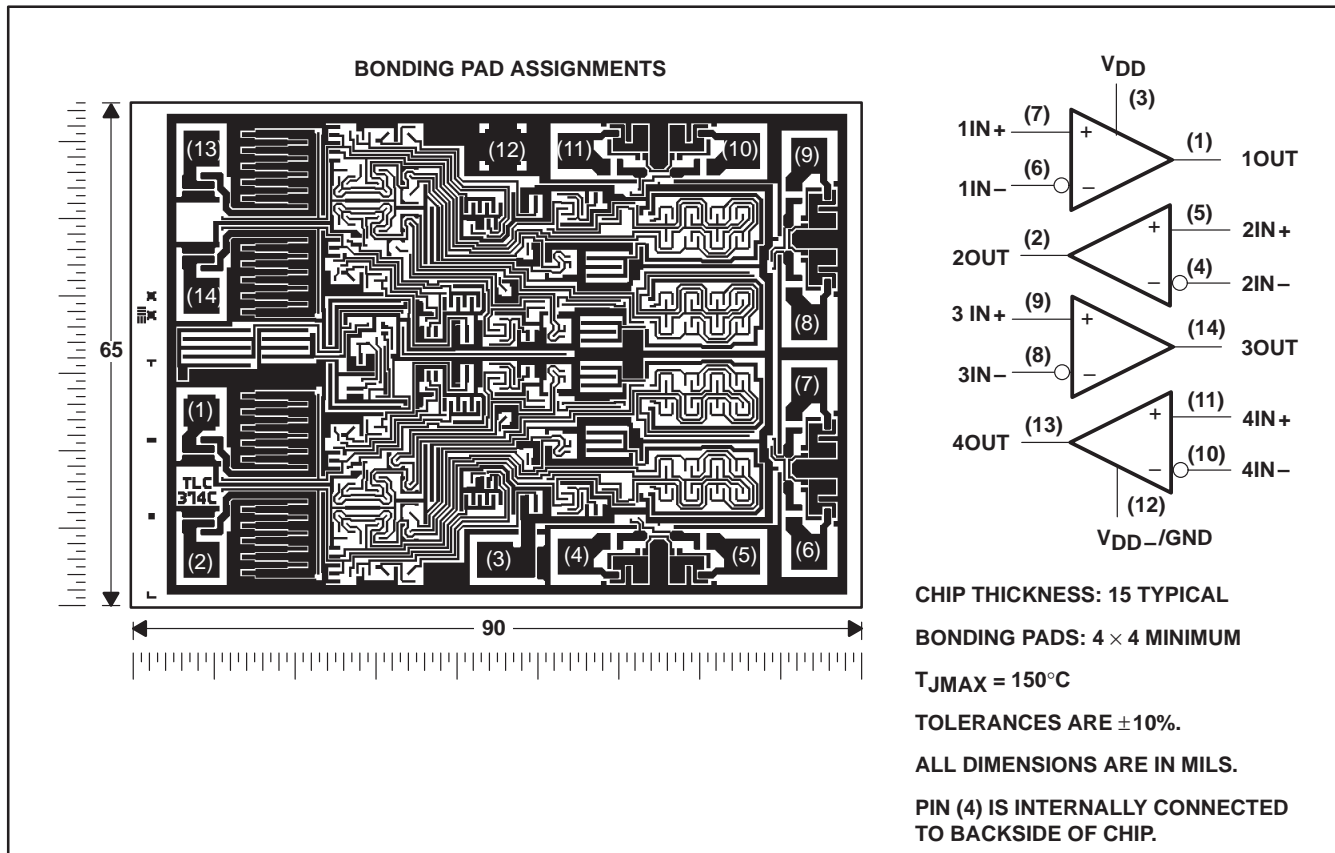
TLC354

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TLC364Y chip information

This chip, when properly assembled, displays characteristics similar to the TLC354C. Thermal compression or ultrasonic bonding can be used on the doped-aluminum bonding pads. Chips can be mounted with conductive epoxy or a gold-silicon preform.



recommended operating conditions

		TLC354C		TLC354I		TLC354M		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Supply voltage, V _{DD}		1.4	16	1.4	16	1.4	16	V
Common-mode input voltage, V _{IC}	V _{DD} = 1.4 V	0	0.2	0	0.2	0	0.2	V
	V _{DD} = 5 V	0	3.5	0	3.5	0	3.5	
	V _{DD} = 10 V	0	8.5	0	8.5	0	8.5	
Operating free-air temperature, T _A		0	70	-40	85	-55	125	°C

electrical characteristics at specified free-air temperature, V_{DD} = 1.4 V

PARAMETER		TEST CONDITIONS		T _A †	TLC354C			TLC354I			TLC354M			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	Input offset voltage	V _{IC} = V _{ICRmin} , See Note 4		25°C	2	5		2	5		2	5	mV	
				Full range			6.5			7				10
I _{IO}	Input offset current			25°C	1			1			1		pA	
				MAX			0.3			1			10	nA
I _{IB}	Input bias current			25°C	5			5			5		pA	
				MAX			0.6			2			20	nA
V _{ICR}	Common-mode input voltage range			25°C	0 to 0.2			0 to 0.2			0 to 0.2		V	
I _{OH}	High-level output current	V _{ID} = 1 V	V _{OH} = 5 V	25°C	0.1			0.1			0.1		nA	
			V _{OH} = 15 V	Full range			1			1			1	µA
V _{OL}	Low-level output voltage	V _{ID} = -0.5 V, I _{OL} = 0.6 mA		25°C	100	200		100	200		100	200	mV	
				Full range			200			200				200
I _{OL}	Low-level output current	V _{ID} = -0.5 V, V _{OL} = 300 mV		25°C	1	1.6		1	1.6		1	1.6	mA	
I _{DD}	Supply current (four comparators)	V _{ID} = 0.5 V, No load		25°C	130	300		130	300		130	300	µA	
				Full range			400			400				400

† All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70°C for TLC354C, -40°C to 85°C for TLC354I, and -55°C to 125°C for the TLC354M. MAX is 70°C for TLC354C, 85°C TLC354I, and 125°C for the TLC354M. IMPORTANT: See Parameter Measurement Information.

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-kΩ resistor between the output and V_{DD}. They can be verified by applying the limit value to the input and checking for the appropriate output state.

electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$

PARAMETER	TEST CONDITIONS	T_A †	TLC354C			TLC354I			TLC354M			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		
V_{IO} Input offset voltage	$V_{IC} = V_{ICRmin}$, See Note 5	25°C		2	5		2	5		2	5	mV	
		Full range			6.5			7			10		
I_{IO} Input offset current		25°C		1			1			1		pA	
		MAX			0.3			1			10	nA	
I_{IB} Input bias current		25°C		5			5			5		pA	
		MAX			0.6			2			20	nA	
V_{ICR} Common-mode input voltage range		25°C	0 to $V_{DD}-1$			0 to $V_{DD}-1$			0 to $V_{DD}-1$			V	
		Full range	0 to $V_{DD}-1.5$			0 to $V_{DD}-1.5$			0 to $V_{DD}-1.5$				
I_{OH} High-level output current	$V_{ID} = 1\text{ V}$	$V_{OH} = 5\text{ V}$	25°C	0.1			0.1			0.1			nA
		$V_{OH} = 15\text{ V}$	Full range							1			μA
V_{OL} Low-level output voltage	$V_{ID} = -1\text{ V}$, $I_{OL} = 4\text{ mA}$	25°C		150	400		150	400		150	400	mV	
		Full range		700			700			700			
I_{OL} Low-level output current	$V_{ID} = -1\text{ V}$, $V_{OL} = 1.5\text{ mV}$	25°C	6	16		6	16		6	16	mA		
I_{DD} Supply current (four comparators)	$V_{ID} = 1\text{ V}$, No load	25°C		0.3	0.6		0.3	0.6		0.3	0.6	mA	
		Full range		0.8			0.8			0.8			

† All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70 °C for TLC354C, –40°C to 85°C for TLC354I, and –55°C to 125°C for the TLC354M. MAX is 70°C for TLC354C, 85°C TLC354I, and 125°C for the TLC354M. IMPORTANT: See Parameter Measurement Information.

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a 10-k Ω resistor between the output and V_{DD} . They can be verified by applying the limit value to the input and checking for the appropriate output state.

switching characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TLC354C, TLC354I TLC354M			UNIT
		MIN	TYP	MAX	
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}$ ‡, See Note 6	100-mV input step with 5-mV overdrive			ns
		TTL-level input step			

‡ C_L includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

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electrical characteristics at specified free-air temperature, $V_{DD} = 1.4\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{IC} = V_{ICR} \text{ min, See Note 4}$		2	5	mV
I_{IO} Input offset current			1		pA
I_{IB} Input bias current			5		pA
V_{ICR} Common-mode input voltage range		0 to 0.2			V
I_{OH} High-level output current	$V_{ID} = 1\text{ V, } V_{OH} = 5\text{ V}$		0.1		nA
V_{OL} Low-level output voltage	$V_{ID} = -0.5\text{ V, } I_{OL} = 0.6\text{ mA}$		100	200	mV
I_{OL} Low-level output current	$V_{ID} = -0.5\text{ V, } V_{OL} = 300\text{ mV}$	1	1.6		mA
I_{DD} Supply current (four comparators)	$V_{ID} = 0.5\text{ V, No load}$		130	300	μA

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-k Ω resistor between the output and V_{DD} . They can be verified by applying the limit value to the input and checking for the appropriate output state.

electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{IC} = V_{ICR} \text{ min, See Note 5}$		2	5	mV
I_{IO} Input offset current			1		pA
I_{IB} Input bias current			5		pA
V_{ICR} Common-mode input voltage range		0 to $V_{DD}-1$			V
I_{OH} High-level output current	$V_{ID} = 1\text{ V, } V_{OH} = 5\text{ V}$		0.1		nA
V_{OL} Low-level output voltage	$V_{ID} = -1\text{ V, } I_{OL} = 4\text{ mA}$		150	400	mV
I_{OL} Low-level output current	$V_{ID} = -1\text{ V, } V_{OL} = 1.5\text{ mV}$	6	16		mA
I_{DD} Supply current (four comparators)	$V_{ID} = 1\text{ V, No load}$		0.3	0.6	mA

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a 10-k Ω resistor between the output and V_{DD} . They can be verified by applying the limit value to the input and checking for the appropriate output state.

switching characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}^\ddagger$, See Note 6	100-mV input step with 5-mV overdrive			ns
		TTL-level input step			

$^\ddagger C_L$ includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



PARAMETER MEASUREMENT INFORMATION

The digital output stage of the TLC354 can be damaged if it is held in the linear region of the transfer curve. Conventional operational amplifier/comparator testing incorporates the use of a servo loop that is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, the following alternative for measuring parameters such as input offset voltage, common-mode rejection, etc., are offered.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 1(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed as shown in Figure 1(b) for the V_{ICR} test, rather than changing the input voltages, to provide greater accuracy.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal but opposite in polarity to the input offset voltage, the output changes state.

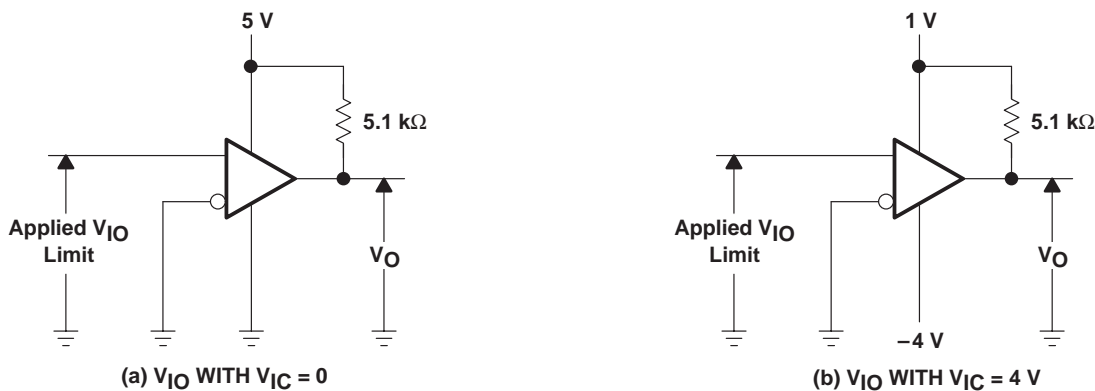


Figure 1. Method for Verifying That Input Offset Voltage is Within Specified Limits

PARAMETER MEASUREMENT INFORMATION

Figure 2 illustrates a practical circuit for direct dc measurement of input offset voltage that does not bias the comparator into the linear region. The circuit consists of a switching-mode servo loop in which U1a generates a triangular waveform of approximately 20-mV amplitude. U1b acts as a buffer with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by U1c through the voltage divider formed by R9 and R10. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage divider R9 and R10 provides a step up of the input offset voltage by a factor of 100 to make measurement easier. The values of R5, R8, R9, and R10 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be 1% or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open-socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.

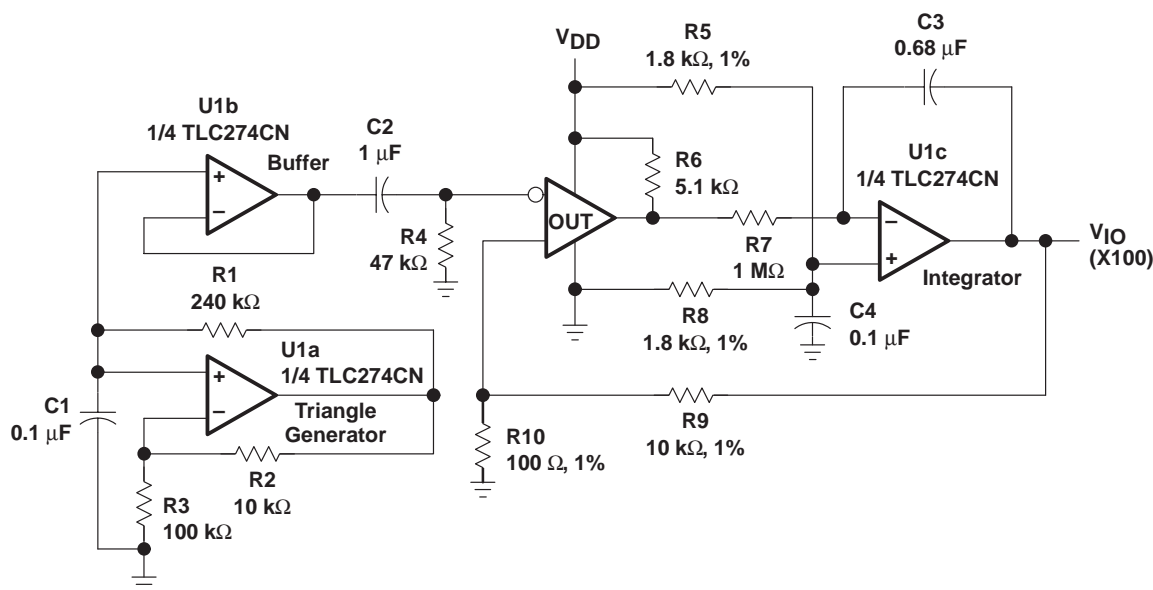
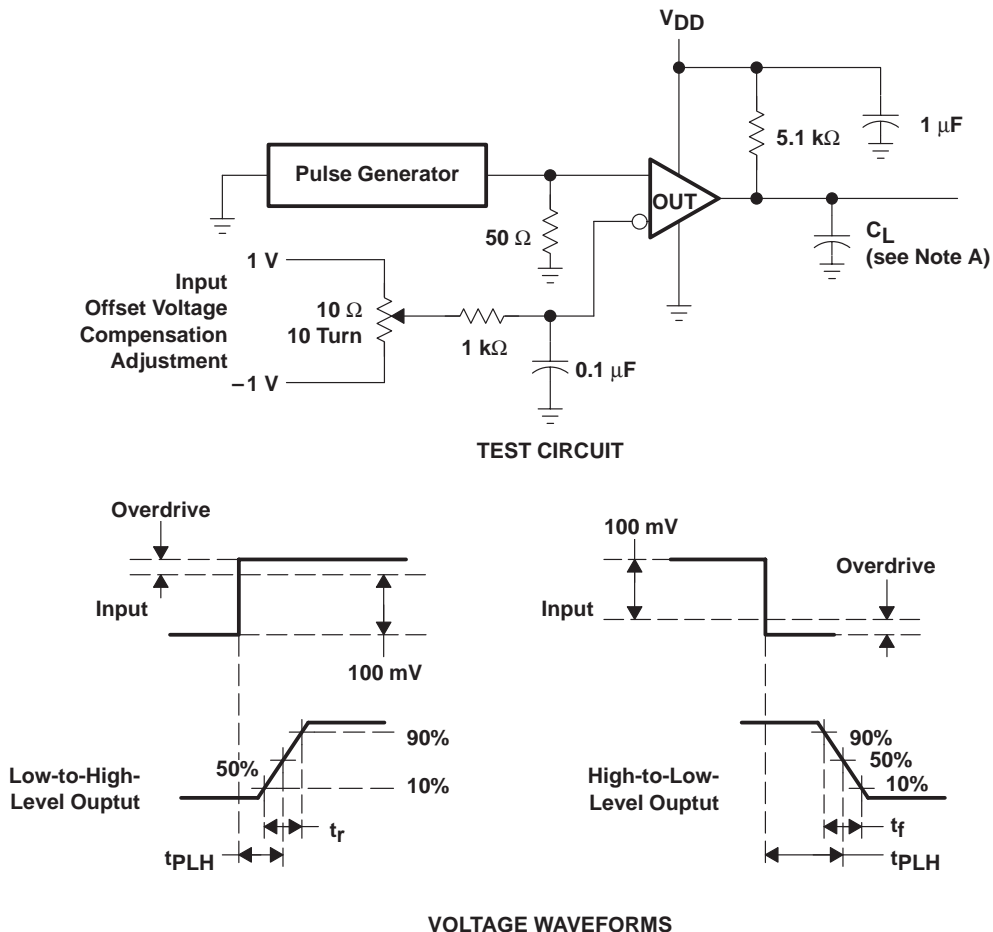


Figure 2. Test Circuit for Input Offset Voltage Measurement

PARAMETER MEASUREMENT INFORMATION

Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time, low-to-high-level output, is measured from the trailing edge of the input pulse. Response-time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input (as shown in Figure 3) so that the circuit is just at the transition point. Then a low signal, for example, 105-mV or 5-mV overdrive, causes the output to change.



NOTE A: C_L includes probe and jig capacitance.

Figure 3. Response, Rise, and Fall Times Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC354CD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC354C	Samples
TLC354CN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TLC354CN	Samples
TLC354CPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354CPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354ID	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC354I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC354CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

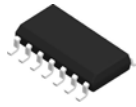
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC354CPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLC354CD	D	SOIC	14	50	505.46	6.76	3810	4
TLC354CN	N	PDIP	14	25	506	13.97	11230	4.32
TLC354CPW	PW	TSSOP	14	90	530	10.2	3600	3.5
TLC354ID	D	SOIC	14	50	505.46	6.76	3810	4

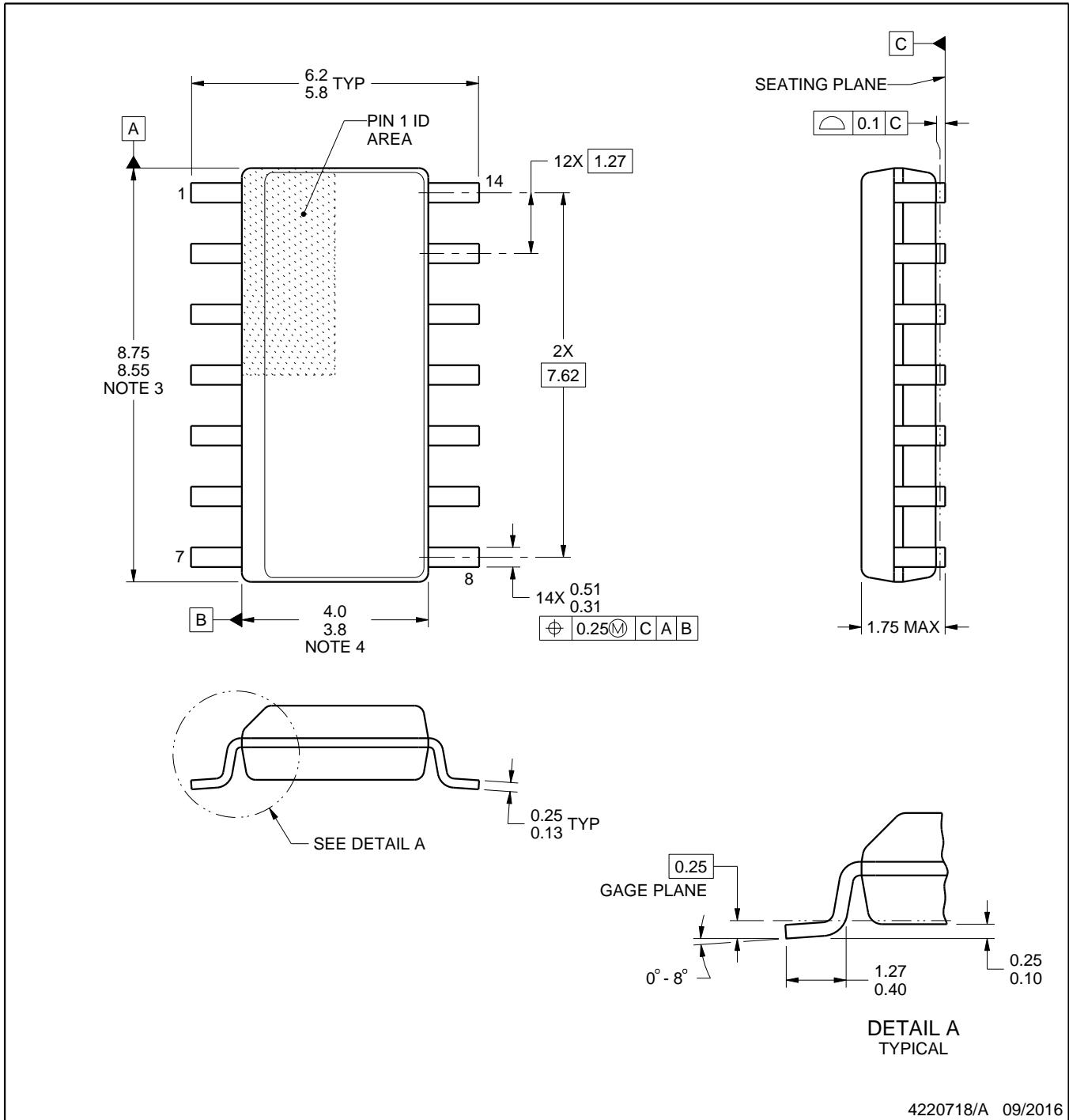
D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

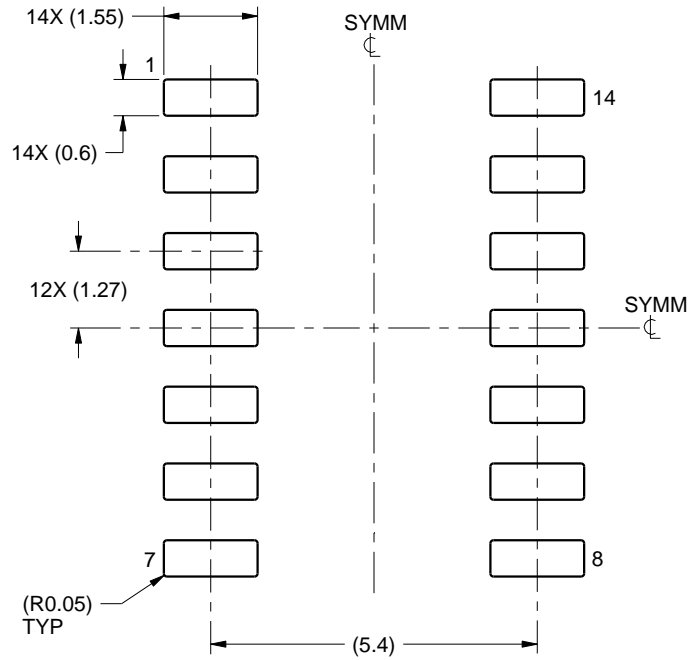
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

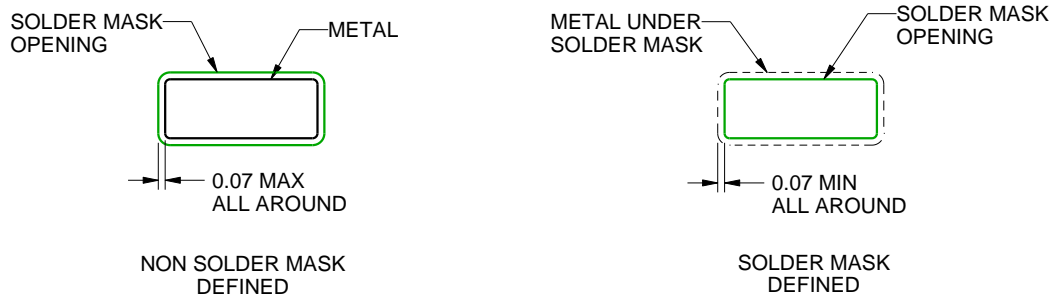
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SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

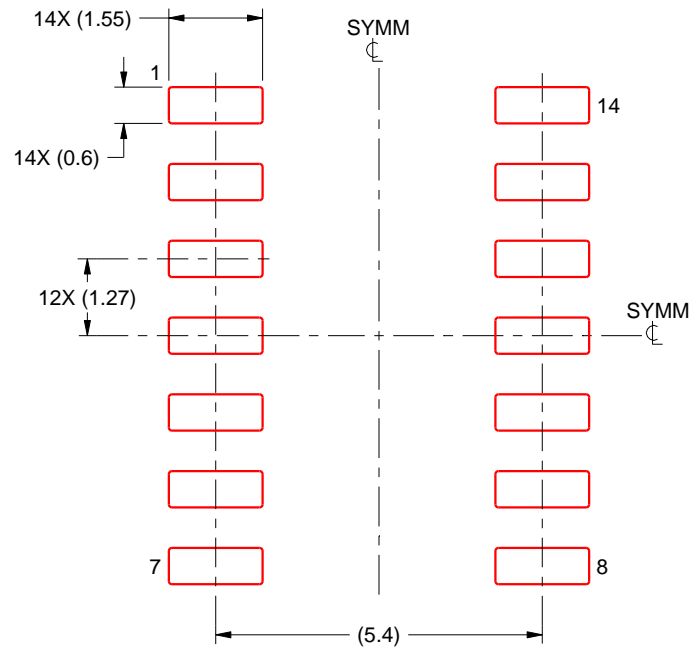
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



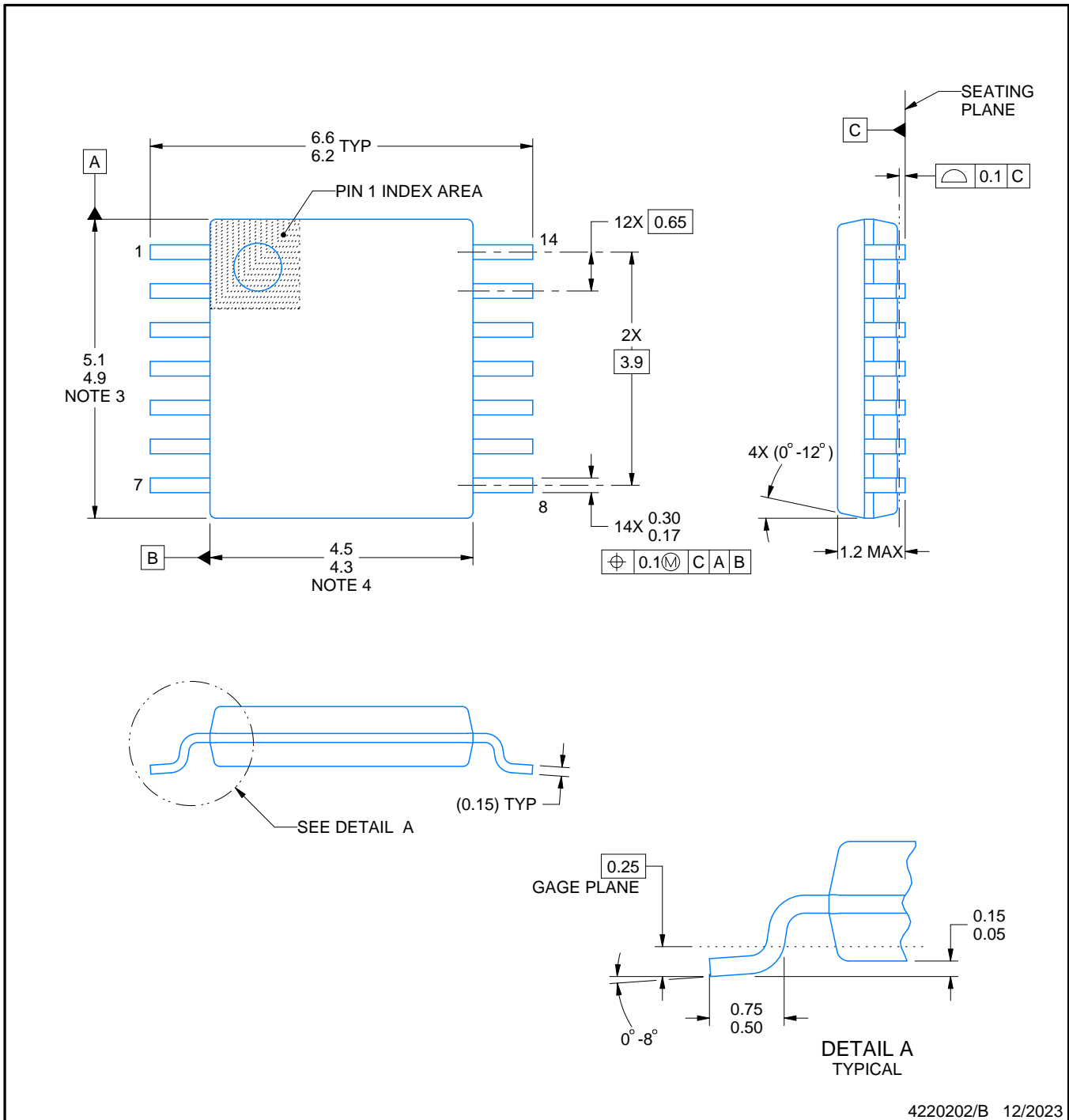
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW0014A



PACKAGE OUTLINE
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



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NOTES:

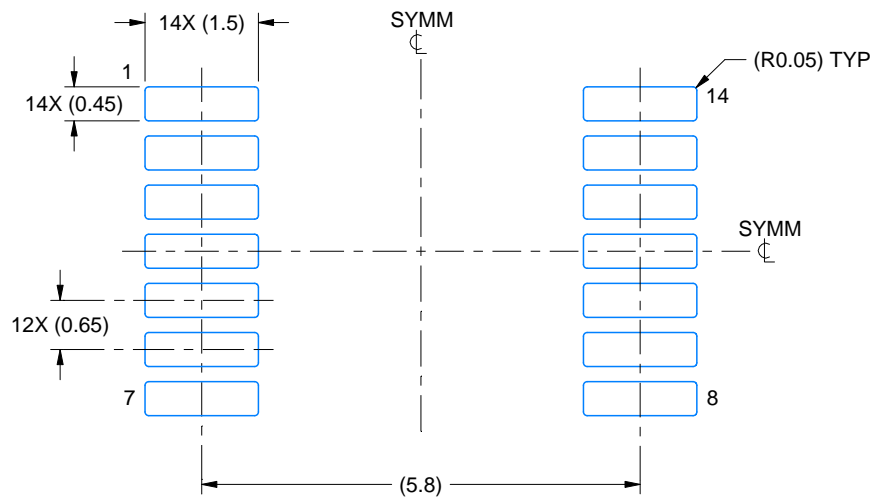
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

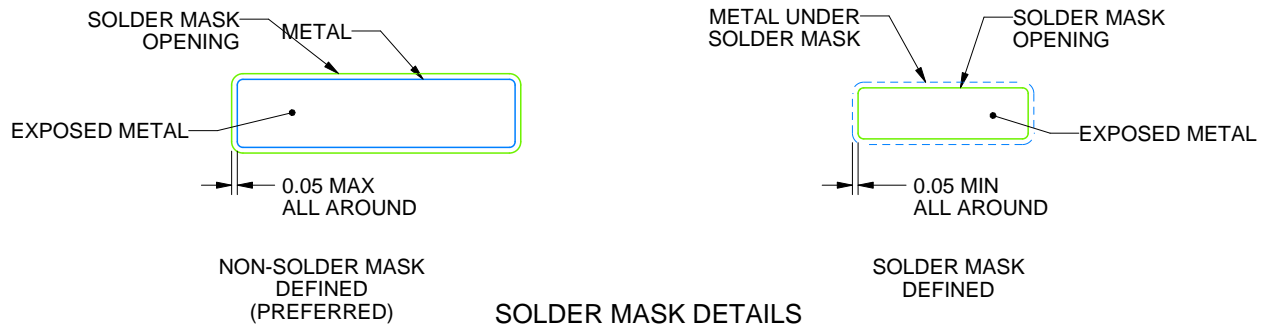
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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